

ABSTRACT OF THE DISCLOSURE

The semiconductor device includes an input/output circuit, a functional module, an electrostatic discharge protection circuit and bumps. The

5      input/output circuit is formed close to an edge of the semiconductor chip. The functional module is formed on the semiconductor chip located on a central side with regard to the input/output circuit. The electrostatic discharge protection circuit is formed in the

10     functional module of the semiconductor chip and serves to protect a circuit located in a downstream thereof, from being destructed by electrostatic discharge. The bumps are arranged on one of major surfaces of the semiconductor chip located close to the functional

15     module, and they are connected to the functional module via the electrostatic discharge protection circuit.